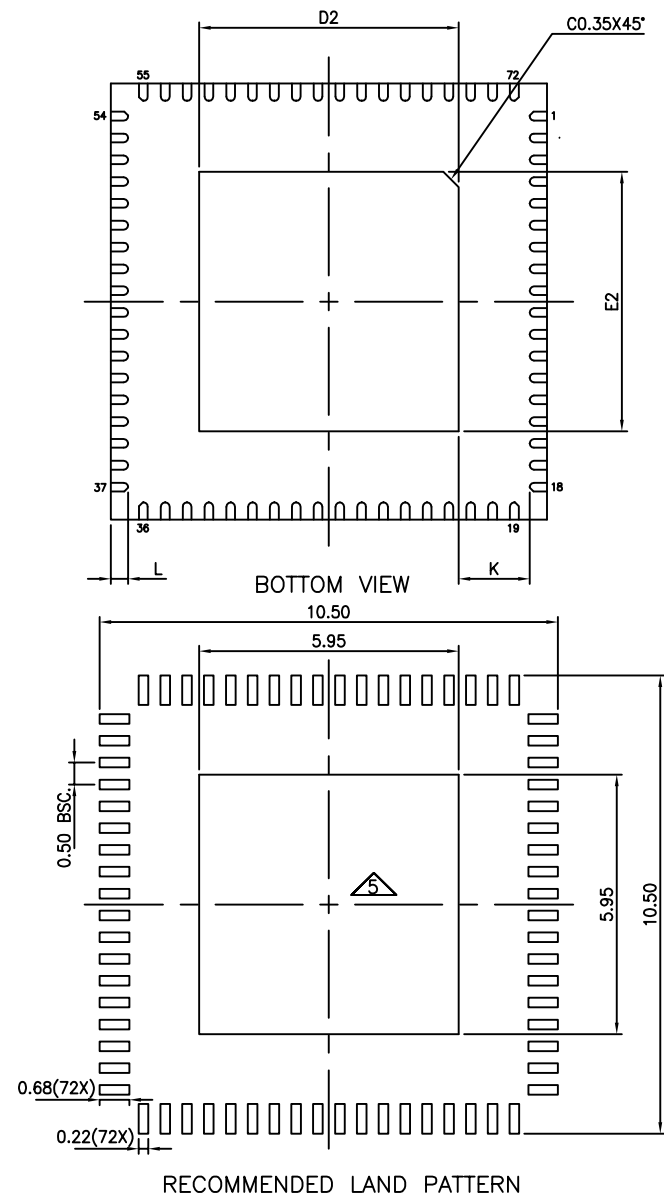
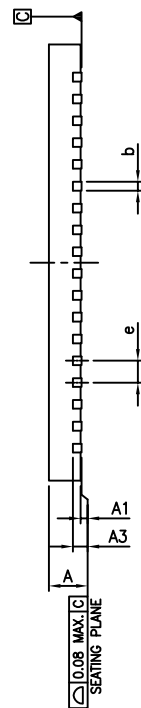


SYMBOLS	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.203 REF.		
b	0.15	0.20	0.25
D	9.90	10.00	10.10
E	9.90	10.00	10.10
e	0.50 BSC		
L	0.30	0.40	0.50
K	0.20	—	—
D2	5.90	5.95	6.00
E2	5.90	5.95	6.00



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

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DATE: 09/12/18

DESCRIPTION: 72-Contact, TQFN

PACKAGE CODE: ZD (ZD72)

DOCUMENT CONTROL #: PD-2037

REVISION: E